

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

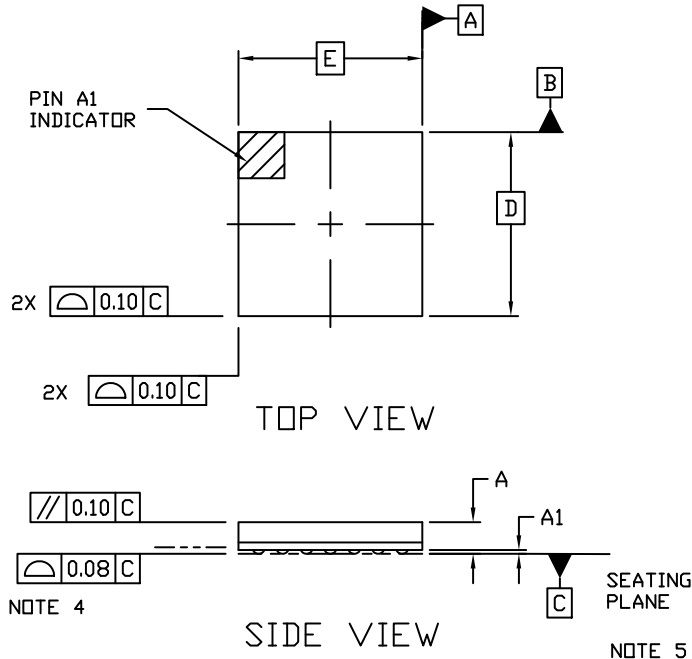
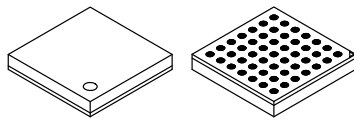


LFBGA49 5x5 / FBGA49

CASE 566DD

ISSUE A

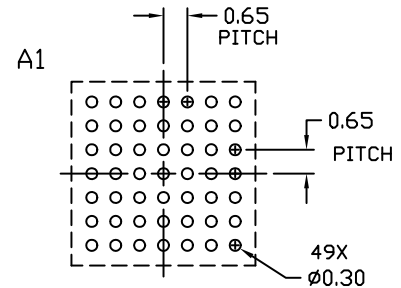
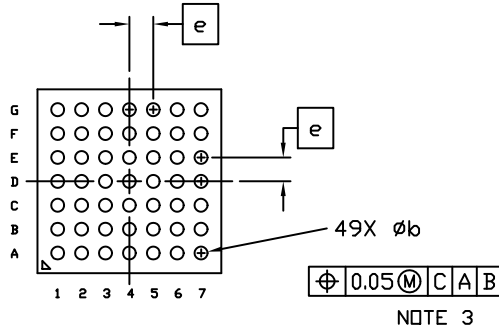
DATE 28 JAN 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

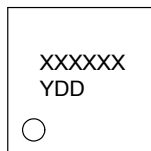
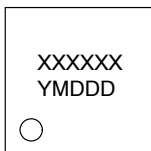
DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.95
A1	0.05	0.15
<i>b</i>	0.30	0.40
D	5.00 BSC	
E	5.00 BSC	
<i>e</i>	0.65 BSC	



BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

XXXXX = Specific Device Code
Y = Year
DD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	LFBGA49 5X5 / FBGA49	PAGE 1 OF 2

